

08-14-2006



To the Commissioner For Patent

103290677

nents or copy thereof.

1. Name of conveying party(ies):

Norman A. Card, Richard A. Day, John J. Konrad

Additional names of conveying party(ies) attached?

Yes ☒ No ☒

3. Nature of Conveyance

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 08/03/06; 08/04/06

2. Name and address of receiving party(ies):

Name: Endicott Interconnect Technologies, Inc.

Street Address: 1701 North Street

City: Endicott

State: New York Zip 13760

Additional name(s) & address(es) attached?

Yes ☐ No ☒

4. Application number(s) or patent number(s):

Title: Improved Solder Mask Application Process

If this document is being filed together with a new application, the execution date of the application is 08/03/06; 08/04/06

A. Patent Application No(s):

B. Patent No(s):

Additional numbers attached?

Yes ☐ No ☒

ATTORNEY DOCKET NUMBER EI-2-06-007

5. Name and address of party to whom correspondence concerning document should be mailed:

Hinman, Howard & Kattell, LLP
700 Security Mutual Building
80 Exchange Street
Binghamton, New York 13901

Att: Lawrence R. Fraley

6. Total number of applications and patents involved: (No.)

7. Total fee (37 CVF 3.41): \$40.00

☒ Enclosed

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8. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley

Name of Person Signing

Signature

08/07/06

Date

Registration # 26,885

Tel: 561-575-3608

Total number of pages comprising cover sheet: 2

ASSIGNMENT

EI-2-06-007

Whereas, We

- | | | |
|-----|------------------------------------|--|
| (1) | Norman A. Card
County of Tioga | City of Lockwood
And State of New York |
| (2) | Richard A. Day
County of Broome | City of Whitney Point
And State of New York |
| (3) | John J. Konrad
County of Broome | City of Endicott
And State of New York |

have invented certain improvements in Improved Solder Mask Application Process and have executed, respectively, a United States patent application therefor on

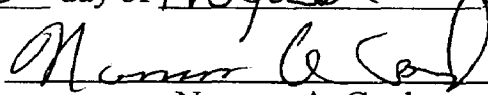
(1) 8/03/06 , (2) 8/4/06 , (3) 8/3/06

And whereas, ENDICOTT INTERCONNECT TECHNOLOGIES, INC., a corporation of New York, having a place of business at Endicott, New York 13760, (hereinafter called EI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

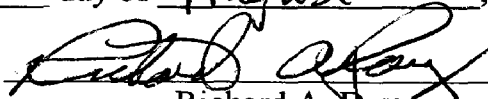
Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to EI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for protection in the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to EI, its successors and assigns; and we hereby agree that EI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by EI.

Signed:

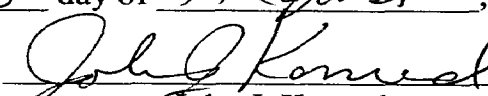
at Endicott, New York, this 3 day of August, 2006.


Norman A. Card

at Endicott, New York, this 4 day of August, 2006.


Richard A. Day

at Endicott, New York, this 3 day of August, 2006.


John J. Konrad